

General Description

SFGMOS[®] MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

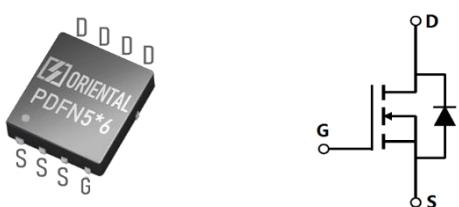
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	100	V
$I_D, pulse$	120	A
$R_{DS(ON) max} @ V_{GS}=10V$	20	mΩ
Q_g	19.8	nC

Marking Information

Product Name	Package	Marking
SFG10R20GF	PDFN5*6	SFG10R20G

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	40	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	120	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	40	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	120	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	72	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	30	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.74	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		17	20	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=8 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$			26	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=6 \text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=100 \text{ V}, V_{GS}=0 \text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		1191		pF	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		195		pF	
Reverse transfer capacitance	C _{rss}		4.1		pF	
Turn-on delay time	t _{d(on)}		17.8		ns	V _{GS} =10 V, V _{DS} =50 V, R _G =2.2 Ω, I _D =10 A
Rise time	t _r		3.9		ns	
Turn-off delay time	t _{d(off)}		33.5		ns	
Fall time	t _f		3.2		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		19.8		nC	V _{GS} =10 V, V _{DS} =50 V, I _D =8 A
Gate-source charge	Q _{gs}		2.4		nC	
Gate-drain charge	Q _{gd}		5.3		nC	
Gate plateau voltage	V _{plateau}		3.2		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =8 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		50.2		ns	V _R =50 V, I _S =8 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		95.1		nC	
Peak reverse recovery current	I _{rrm}		2.5		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=30 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

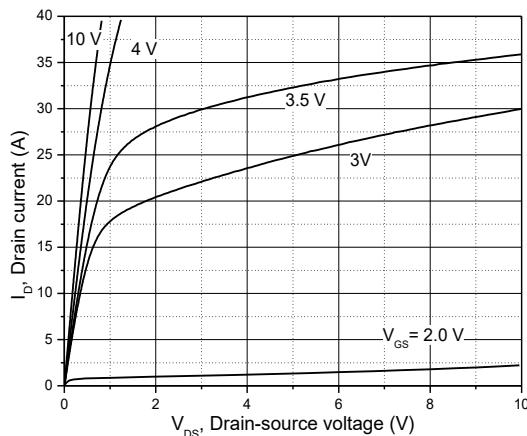


Figure 1. Typ. output characteristics

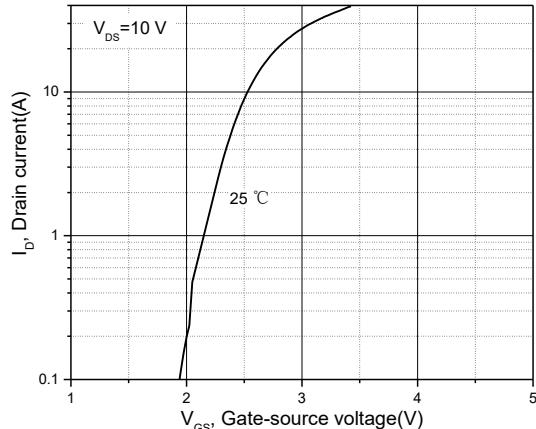


Figure 2. Typ. transfer characteristics

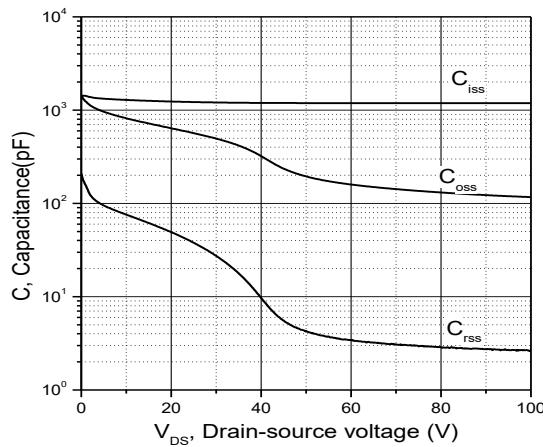


Figure 3. Typ. capacitances

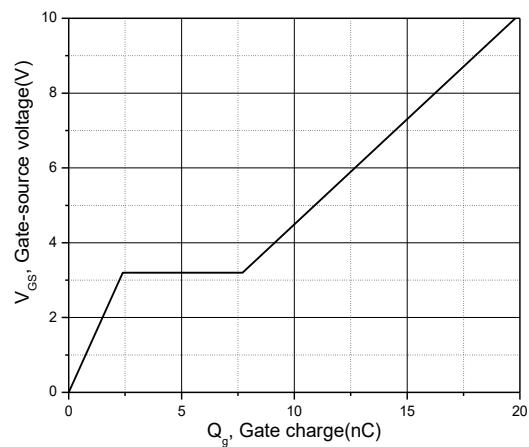


Figure 4. Typ. gate charge

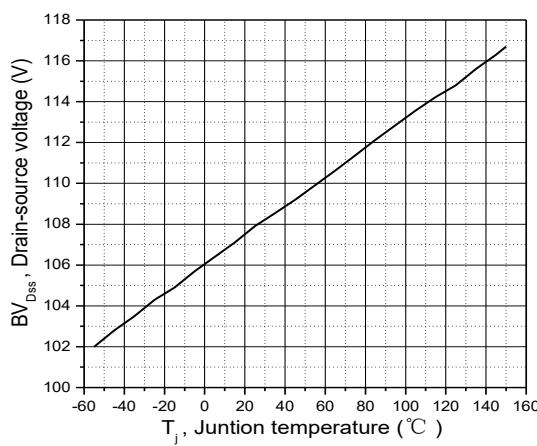


Figure 5. Drain-source breakdown voltage

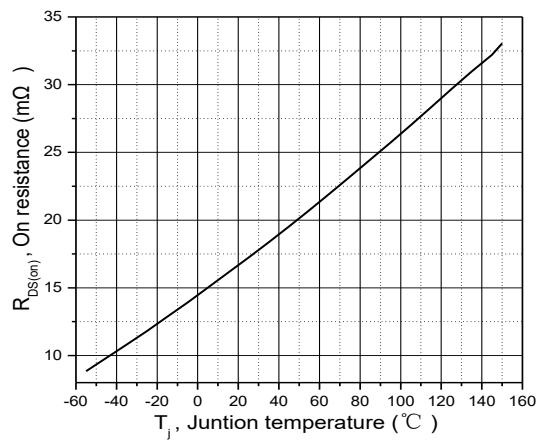


Figure 6. Drain-source on-state resistance

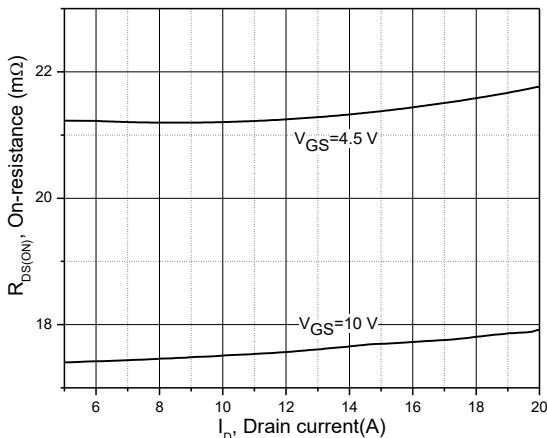


Figure 7. Drain-source on-state resistance

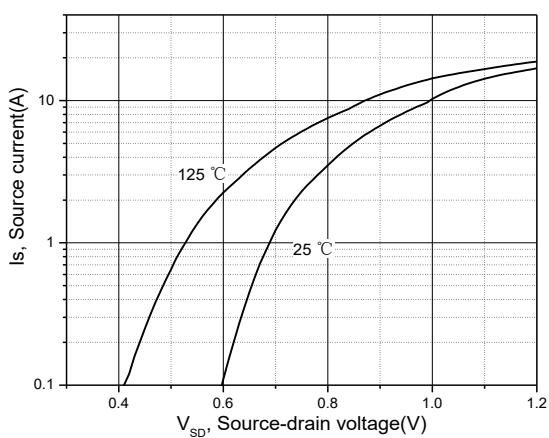


Figure 8. Forward characteristic of body diode

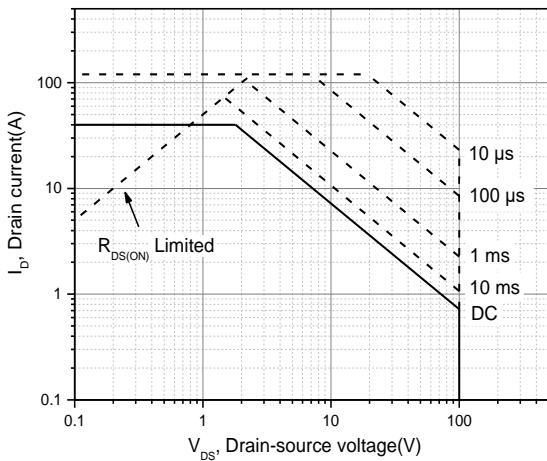


Figure 9. Safe operation area $T_c=25\text{ }^{\circ}\text{C}$

Test circuits and waveforms

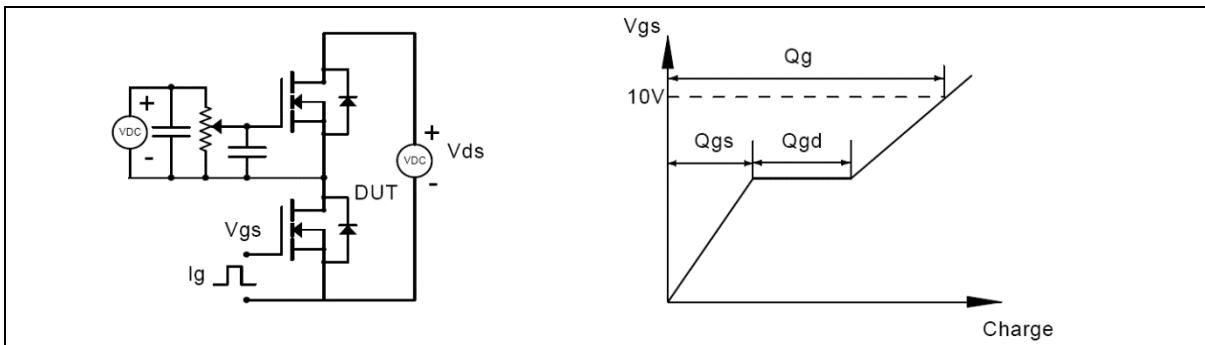


Figure 1. Gate charge test circuit & waveform

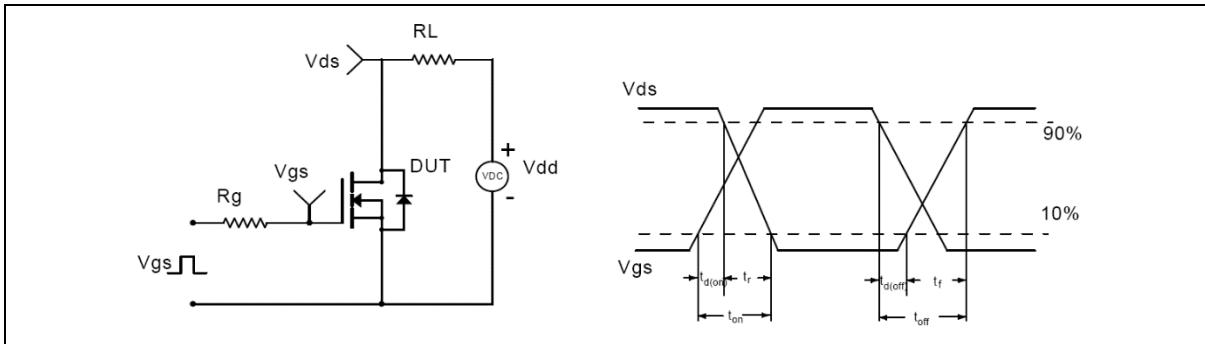


Figure 2. Switching time test circuit & waveforms

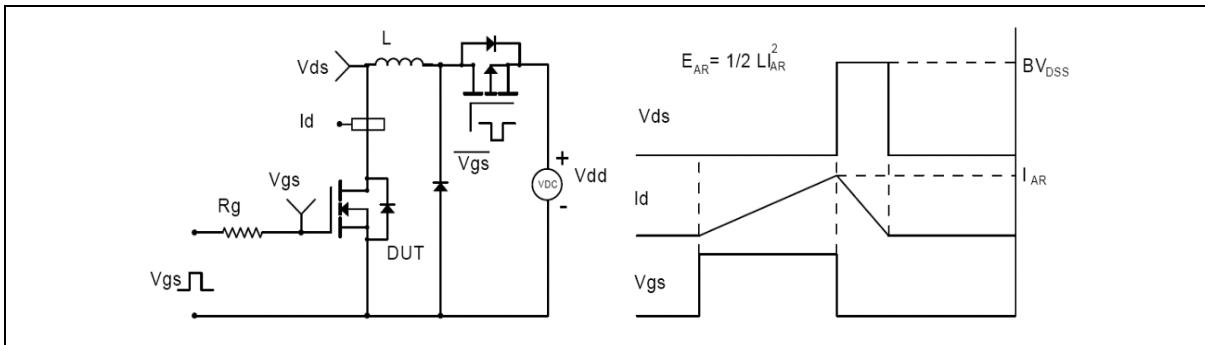


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

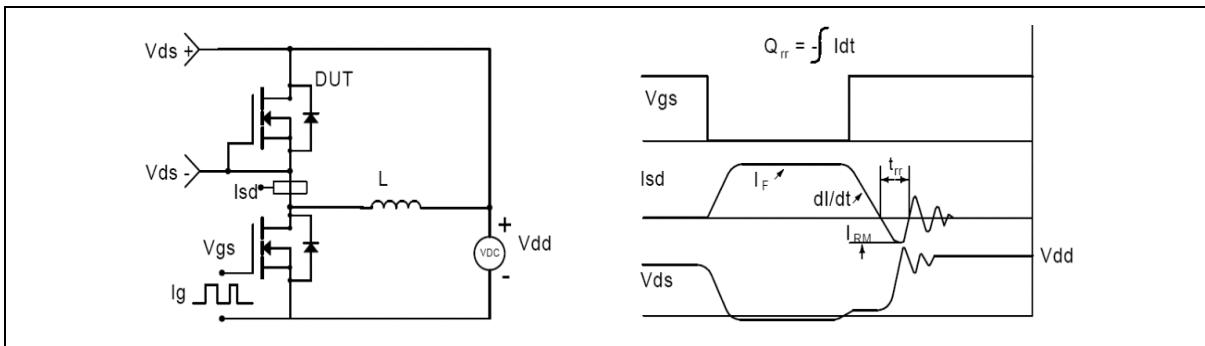
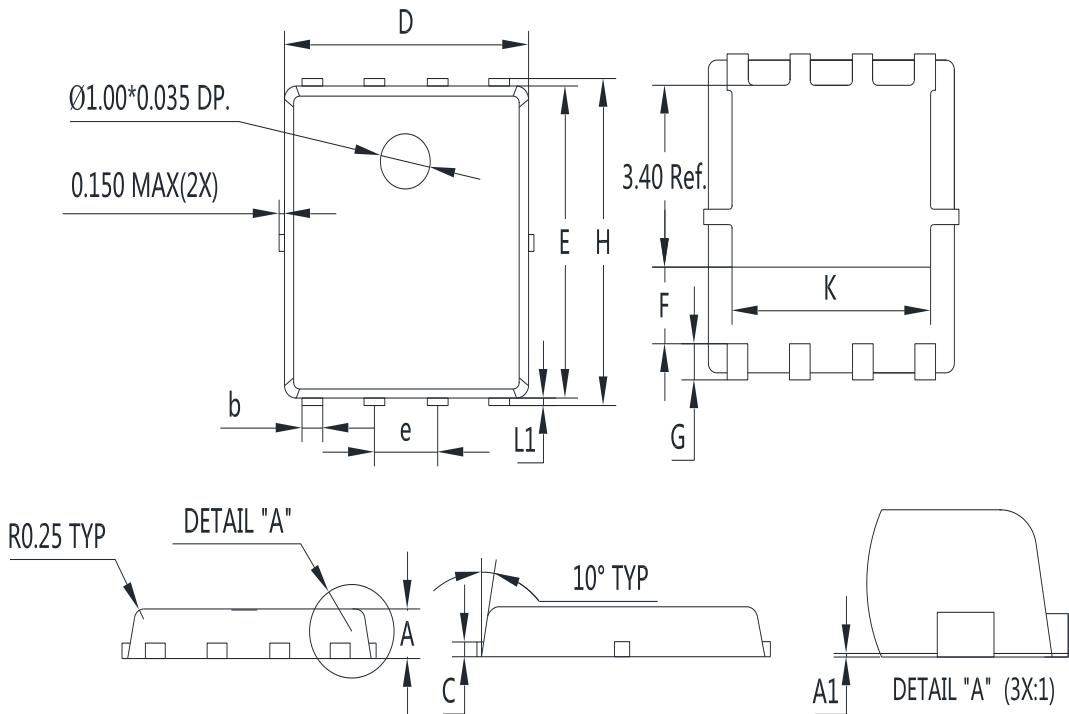


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	0.8	0.9	1.0
A1	0	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF		
D	4.9	5.0	5.1
F	1.40 REF		
E	5.7	5.8	5.9
e	1.27 BSC		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF		
K	4.00 REF		

Version 1: PDFN5*6-K package outline dimension

Ordering Information

Package Type	Units/Reel	Reels / Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN5*6-K	5000	2	10000	5	50000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG10R20GF	PDFN5*6	yes	yes	yes

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